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H8SX Family

Using the DMAC to Drive Continuous SCI Reception in Clock Synchronous Mode

Introduction

Clock synchronous transfer is used to transmit and receive 128 bytes of data. Using the DMAC to handle the transfer (reception) of data enables continuous reception with no CPU intervention.

Target Device

H8SX/1653

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1. Specification

Clock synchronous transfer is used to receive 128 bytes of data. Using the DMAC to handle the transfer (reception) of data enables continuous reception with no CPU intervention.

- An example of connection for this sample task is shown in figure 1.
- Table 1 shows the communications format.
- After a power-on reset of the transmitting side, the state of P13 pin is polled. When the P13 pin is a high level, the transmitting side judges the transfer is enabled at the receiving side, after which operations for the clock synchronous transmission of 128 bytes of data proceed.
- After a power-on reset of the receiving side, the SCI and DMAC functions are set up. The same side outputs a highlevel signal on pin P13, after which operations for the clock synchronous reception of 128 bytes of data proceed in synchronization with the transmitting-side clock input on pin SCK.

In this sample task, the DMAC module is interrupt-activated to handle consecutive reception of the 128 bytes of data.

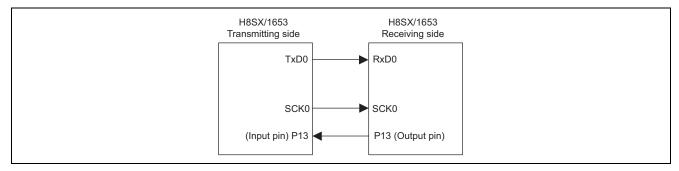


Figure 1 Clock Synchronous Serial Reception

Table 1 Format for Clock Synchronous Serial Reception

Setting
32 MHz
Clock synchronous
External clock
250 kbps
8 bits
LSB first

2. Applicable Conditions

Table 2 Applicable Conditions

Item	Description	
Operating frequency	Input clock	: 16 MHz
	System clock (I)	: 32 MHz (input clock frequency × 2)
	Peripheral mode clock (P)	: 32 MHz (input clock frequency × 2)
	External bus clock (Βφ)	: 32 MHz (input clock frequency × 2)
Mode of operation	Mode 6 (MD2 = 1, MD1 = 1, M	MD0 = 0, MD_CLK = 0)



3. Description of Modules Used

3.1 Description in Outline

Peripheral modules of the H8SX/1653 which are used in this sample task are shown in Figure 2.

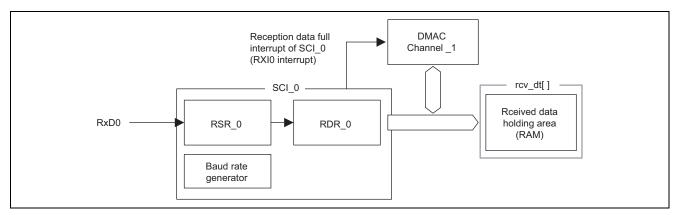


Figure 2 Functions of the H8SX/1653

The description which concerns the blocks shown in figure 2 is stated below.

1. SCI 0

Receives data with timing provided by the clock synchronous communications.

- After one frame of data has been received via the RxD0 pin, the received data are transferred from RSR_0 to RDR_0.
- Once the data have been successfully received and then transferred from RSR_0 to RDR_0, a reception data full interrupt (RXI interrupt) from SCI 0 is generated.

2. DMAC channel 1

• Channel 1 is activated by the received data full interrupt (RXI0 interrupt) from SCI_0 and transfers data from RDR_0 to the area where received data is to be stored.



3.2 Description of SCI_0

In this sample task, SCI_0 is used for clock synchronous serial data reception. Figure 3 is a block diagram of SCI_0.

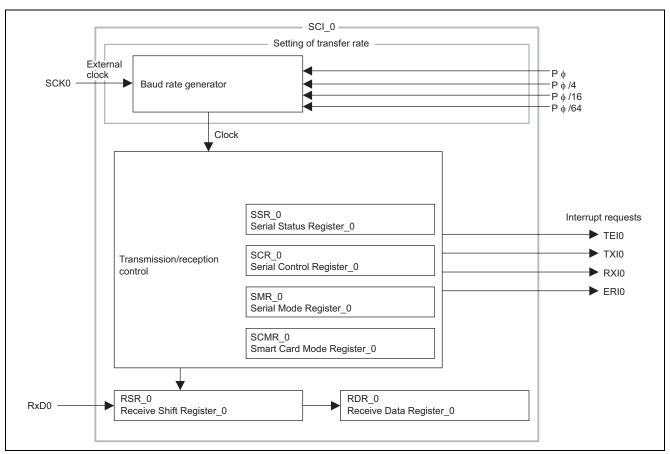


Figure 3 Block Diagram of SCI_0



The description which concerns the blocks shown in figure 3 is stated below.

- On-chip peripheral clock Pφ

 This is the base clock for the operation of on-chip peripheral functions and is generated by a clock oscillator.
- Receive shift register_0 (RSR_0)
 RSR_0 is used to receive serial data. Serial data on RSR_0 are input via the RxD0 pin. When one frame of data has been received, the data bits are automatically transferred to the receive data register (RDR_0). RSR_0 is not accessible by the CPU.
- Receive data register_0 (RDR_0)
 RDR_0 is an 8-bit register and used to store received data. After RSR_0 has received one frame, the data bits are automatically transferred from RSR_0 to RDR_0. Since RSR_0 and RDR_0 function as a double buffer, continuous reception is possible. RDR_0 is for reception only, and so is seen as a read-only register by the CPU.
- Serial mode register_0 (SMR_0)
 SMR_0 is an 8-bit register and used to select the format of serial data communications and the clock source for the on-chip baud-rate generator.
- Serial control register_0 (SCR_0)
 SCR_0 is used to control transmission, reception and interrupts, and to select the clock source for transmission and reception.
- Serial status register_0 (SSR_0)
 SSR_0 consists of status flags for SCI_0 and multiprocessor bits for transmission and reception. TDRE, RDRF, ORER, PER, and FER can only be cleared.
- Smart card mode register_0 (SCMR_0)

 SCMR_0 is used to select the smart-card or normal interface mode for SCMR_0, and to set up the format for the smart-card mode. For this task, the setting in SCMR_0 selects the normal asynchronous or clock synchronous mode.
- Bit rate register_0 (BRR_0)
 BRR_0 is an 8-bit register that is used to adjust the bit rate.



3.3 Channel 1 of the DMAC

In this sample task, DMAC channel 1 is activated by the RXI0 interrupt of SCI_0. A block diagram of the DMAC is given in figure 4.

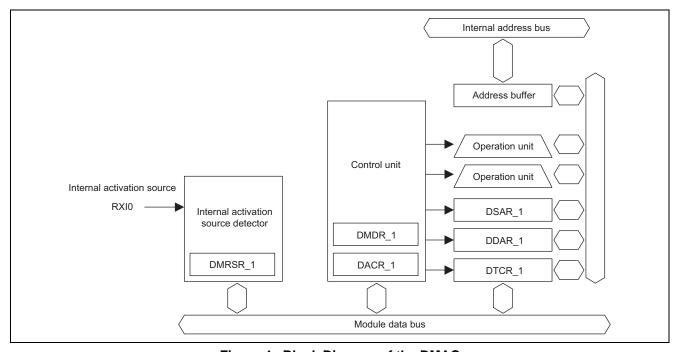


Figure 4 Block Diagram of the DMAC

The description with reference to figure 4 is stated below.

- DMA source address register _1 (DSAR_1)
 DSAR_1 is a 32-bit readable/writable register and specifies the source address for the transfer. The register is equipped with an address-updating function, so the source address is updated to that for the next transfer each time a transfer operation takes place.
- DMA destination address register _1 (DDAR_1)
 DDAR_1 is a 32-bit readable/writable register and specifies the destination address for the transfer. The register is equipped with an address-updating function, so the destination address is updated to that for the next transfer each time a transfer operation takes place.
- DMA transfer count register _1 (DTCR_1)
 DTCR_1 is a 32-bit readable/writable register and specifies the amount of data to be transferred (total size for transfer). After each data transfer operation, the value is reduced by the amount that corresponds to the transferred amount of data. In this sample task, the register is set for 128 bytes of data, and the byte is selected as the unit of data access. One is subtracted from the value on DMAC operation, to indicate the amount still to be transferred.
- DMA mode control register _1 (DMDR_1) DMDR_1 controls DMAC operation.
- DMA address control register_1 (DACR_1)
 DACR_1 sets the operating mode and transfer method.
- DMA module request select register_1 (DMRSR_1)
 DMRSR_1 sets the activation source.



4. Principles of Operation

4.1 Outline

An outline of operation for this sample task is given in figure 5. 128-byte blocks of data are simultaneously transferred in both directions between the transmitting and receiving sides.

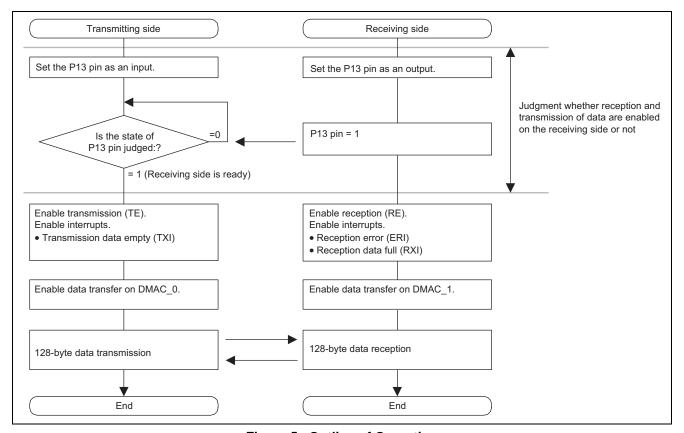


Figure 5 Outline of Operation



4.2 Reception

The timing of reception operation is illustrated in figure 6. Table 3 is a list of the hardware and software processing at the numbered points in figure 6.

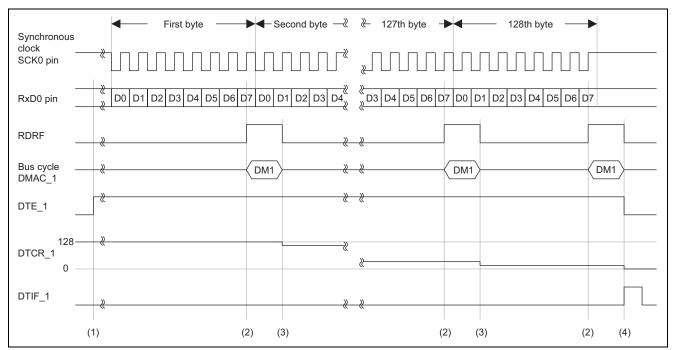


Figure 6 Timing of Reception



Table 3 Processing

Hardware Processing			Software Processing			
(1)	Powe	r-on reset	Initial settings*			
(2)	a.	Set RDRF to 1.	No pro	ocessing		
	 b. End transmission normally and transfer the received data from RSR_0 to RDR_0. c. Activate DMAC_1 and transfer the received data from RDR_0 to received data holding area. 					
(3)	a.	Clear RDRF0 to 0.	No pro	ocessing		
	b.	DTCR_1 counts down.				
(4)	a.	DTCR_0 counts down (DTCR_1 = 0).	DMAC	C_1 transfer end interrupt		
			a.	Disable reception of SCI_0 (RE = 0).		
			b.	Disable interrupt requests of RXI0 and ERI0.		
		C.	Disable DMAC_1 transfer end interrupt request.			

Notes: *Initial settings DMAC_1 settings

- a. Source for activation: RXI0 interrupt. The flag (RDRF) for the RXI0 interrupt source is cleared on completion of the DMA transfer.
- b. Source address: Address of RDR_0. Fixed address is selected as the address incrementation or decrementation.
- c. Destination address: First address of the area where the received data are to be stored. Incrementation is selected as the address incrementation or decrementation setting.
- d. Total amount of transfer: 128 bytes
- e. DMA data transfer is enabled. (DTE_1 = 1).

SCR_0 settings

- a. Clock synchronous mode. Set clock source to external clock.
- b. RXI0 interrupt requests are enabled.
- c. Set SCI_0 reception operations enabled.



5. Description of Software

5.1 Operating Environment

Table 4 Operating Environment

Item	Details
Development tool	High-performance Embedded Workshop Ver.4.01.01
C/C++ compiler	H8S, H8/300 Series C/C++ Compiler Ver.6.01.02
	(manufactured by Renesas Technology)
Compiler options	-cpu = h8sxa:24:md, -code = machinecode, -optimize = 1, -regparam = 3,
	-speed = (register, shift, struct, expression)

Table 5 Section Setting

Address	Section Name	Description
H'001000	Р	Program area
	С	Constant area
H'FF2000	В	Non-initialized data area (RAM area)

Table 6 Vector Table for Interrupt Exception Handling

Exception	Handling Source	Vector No.	Vector Address	Function to Interrupt Destination
Reset		0	H'000000	init
DMAC_1	DMTEND1	129	H'000204	dmtend1_int
SCI_0	ERI0	144	H'000240	eri0_int



5.2 List of Functions

Table 7 lists the functions used in this sample task. Figure 7 shows the structure of hierarchy.

Table 7 List of Functions

Function Name	Description
init	Initialization routine:
	Takes the chip out of module stop mode, performs clock settings, and calls the main
	function.
main	Main routine
	Selects clock synchronous SCI. Calls the DMAC1_rcv_init function. Outputs a high-
	level signal on pin P13. Makes settings for transmission and reception of 128 bytes
	of data.
DMAC1_rcv_init	DMAC_1 initialization
	Selects RXI0-interrupt-triggered processing of transfer from the area where received
	data are to be stored.
dmtend1_int	DMAC_1 transfer end interrupt
	Sets SCI_0 reception, RXI0 and ERI0 interrupt requests, and DMAC_1 transfer end
	interrupt requests disabled.
eri0_int	Reception error interrupt
	Writes error data to RAM and initializes SSR_0.

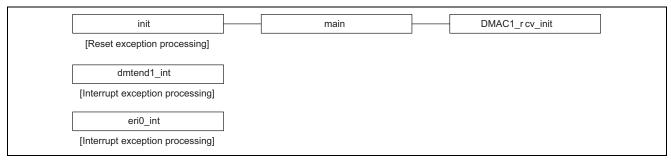


Figure 7 Hierarchy of Calls in the User Program

5.3 RAM Usage

Table 8 RAM Usage

Туре	Variable Name	Description	Used in		
unsigned char errbuf		Reception error buffer	main, eri0_int		
		The contents of SSR_0 are stored when			
		an overrun error occurs.			
unsigned char	rcnt	Reception counter	main, dmtend1_int		
unsigned char	rcv_dt[128]	Received data holding area (RAM)	main, DMAC1_rcv_int		

5.4 Symbolic Constants

Table 9 Symbolic Constants

Constant Name	Setting	Description
NUM	128	Sets the number of data for reception.



5.5 Description of Functions

5.5.1 init Function

1. Functional overview

Initialization routine which releases the required modules from module stop mode, makes clock settings, and calls the main function.

2. Argument

None

3. Return value

None

4. Description of internal registers used

The internal registers used in this sample task are described below. The settings shown in these tables are the values used in this sample task and differ from the initial values.

• Mode control register (MDCR) Number of bits: 16 Address: H'FFFDC0

Bit	Bit Name	Setting	R/W	Description
15	MDS7	Undefined*	R	Indicates the value set by a mode pin (MD3).
				When MDCR is read, the input level on the MD3 pin is
				latched. This latching is released by a reset.
11	MDS3	Undefined*	R	Mode Select 3 to 0
10	MDS2	Undefined*	R	These bits indicate the operating mode selected by the
9	MDS1	Undefined*	R	mode pins (MD2 to MD0) (see table 10). When MDCR is
8	MDS0	Undefined*	R	read, the signal levels input on pins MD2 to MD0 are
				latched into these bits. The latches are released by a reset.

Note: * Determined by the settings on pins MD3 to MD0.

Table 10 Settings of Bits MDS3 to MDS0

MCU	Mode Pi	ns		MDCR			
Operating Mode	MD2	MD1	MD0	MDS3	MDS2	MDS1	MDS0
2	0	1	0	1	1	0	0
4	1	0	0	0	0	1	0
5	1	0	1	0	0	0	1
6	1	1	0	0	1	0	1
7	1	1	1	0	1	0	0

• System clock control register (SCKCR) Number of bits: 16 Address: H'FFFDC4

Bit	Bit Name	Setting	R/W	Description
10	ICK2	0	R/W	System Clock (I) Select
9	ICK1	0	R/W	These bits select the frequency of the system clock signal,
8	ICK0	1	R/W	which is provided to the CPU, DMAC, and DTC.
				001: Input clock × 2
6	PCK2	0	R/W	Peripheral Module Clock (Pφ) Select
5	PCK1	0	R/W	These bits select the frequency of the peripheral module
4	PCK0	1	R/W	clock.
				001: Input clock × 2
2	BCK2	0	R/W	External Bus Clock (B
1	BCK1	0	R/W	These bits select the frequency of the external bus clock.
0	BCK0	1	R/W	001: Input clock × 2



• MSTPCRA, MSTPCRB, and MSTPCRC control module stop mode. Setting a bit to 1 places the corresponding module in module stop mode, while clearing the bit to 0 releases the module from module stop mode.

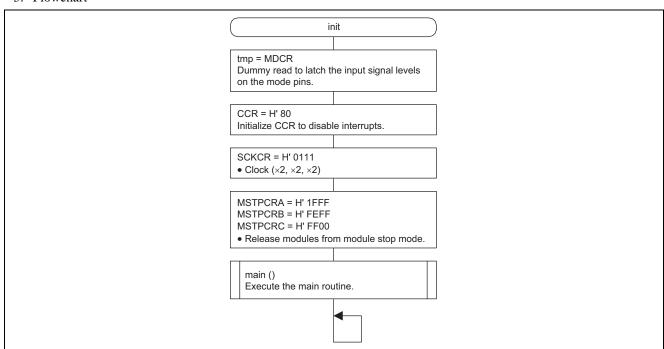
• Mo	Module stop control register A (MSTPCRA)			Number of bits: 16 Address: H'FFFDC8	
Bit	Bit Name	Setting	R/W	Description	
15	ACSE	0	R/W	All-Module-Clock-Stop Mode Enable	
				This bit enables/disables all-module-clock-stop mode for reducing current consumption by stopping the bus controller and I/O port operation when the CPU executes the SLEEP instruction after module stop mode has been set for all of the on-chip peripheral modules controlled by MSTPCR.	
				0: All-module-clock-stop mode disabled	
				1: All-module-clock-stop mode enabled	
13	MSTPA13	0	R/W	DMA controller (DMAC)	
12	MSTPA12	1	R/W	Data transfer controller (DTC)	
9	MSTPA9	1	R/W	8-bit timer unit (TMR_3, TMR_2)	
8	MSTPA8	1	R/W	8-bit timer unit (TMR_1, TMR_0)	
5	MSTPA5	1	R/W	D/A converter (channels 1 and 0)	
3	MSTPA3	1	R/W	A/D converter (unit 0)	
0	MSTPA0	1	R/W	16-bit timer pulse unit (TPU channels 5 to 0)	
Module stop control register B (MSTPCRB)		RB) R/W	Number of bits: 16 Address: H'FFFDCA Description		

Bit	Bit Name	Setting	R/W	Description
15	MSTPB15	1	R/W	Programmable pulse generator (PPG)
12	MSTPB12	1	R/W	Serial communications interface_4 (SCI_4)
10	MSTPB10	1	R/W	Serial communications interface_2 (SCI_2)
9	MSTPB9	1	R/W	Serial communications interface_1 (SCI_1)
8	MSTPB8	0	R/W	Serial communications interface_0 (SCI_0)
7	MSTPB7	1	R/W	I ² C bus interface_1 (IIC_1)
6	MSTPB6	1	R/W	I ² C bus interface_0 (IIC_0)

• Module stop control register C (MSTPCRC) Number of bits: 16 Address: H'FFFDCC

Bit	Bit Name	Setting	R/W	Description
15	MSTPC15	1	R/W	Serial communications interface_5 (SCI_5), (IrDA)
14	MSTPC14	1	R/W	Serial communications interface_6 (SCI_6)
13	MSTPC13	1	R/W	8-bit timer unit (TMR_4, TMR_5)
12	MSTPC12	1	R/W	8-bit timer unit (TMR_6, TMR_7)
11	MSTPC11	1	R/W	Universal serial bus interface (USB)
10	MSTPC10	1	R/W	Cyclic redundancy check module
4	MSTPC4	0	R/W	On-chip RAM_4 (H'FF2000 to H'FF3FFF)
3	MSTPC3	0	R/W	On-chip RAM_3 (H'FF4000 to H'FF5FFF)
2	MSTPC2	0	R/W	On-chip RAM_2 (H'FF6000 to H'FF7FFF)
1	MSTPC1	0	R/W	On-chip RAM_1 (H'FF8000 to H'FF9FFF)
0	MSTPC0	0	R/W	On-chip RAM_0 (H'FFA000 to H'FFBFFF)
				_







5.5.2 main Function

1. Functional overview

Main routine: Sets the clock synchronous SCI, calls the DMAC1_rcv_init function, outputs high-level signal on pin P13, and sets transmission and reception of 128 byte-data.

2. Argument

None

3. Return value

None

4. Description of internal registers used

The internal registers used in this sample task are described below. The settings shown in these tables are the values used in this sample task and differ from the initial values.

Por	t 1 data directio	n register (P1DDR)	Num	ber of bits: 8 Address: Address H'FFFB80	
Bit	Bit Name	Setting	R/W	Description	
3	P13DDR	1	W	0: Sets pin P13 as an input.	
				1: Sets pin P13 as an output.	
• Port 2 input buffer control register (P2ICR) Number of bits: 8 Address: H'FFFB91					
Bit	Bit Name	Setting	R/W	Description	
1	P21ICR	1	R/W	0: P21 (RxD0) pin input buffer is disabled. Input signal is	
				fixed to the high level.	
				1: P21 (RxD0) pin input buffer is enabled. The pin state	
				reflects the peripheral modules.	
0	P20ICR	1	R/W	0: P20 (SCK0) pin input buffer is disabled. Input signal is	
				fixed to the high level.	
				1: P21 (SCK0) pin input buffer is enabled. The pin state	
				reflects the peripheral modules.	
• DM	IA mode contro	l register_1 (DMDR	_1) N	Number of bits: 32 Address: H'FFFC34	
Bit	Bit Name	Setting	R/W	Description	

Bit	Bit Name	Setting	R/W	Description
31	DTE	1	R/W	Data Transfer Enable
				0: Disables data transfer.
				1: Enables data transfer.
-				

•	Port 1 data register	(P1DR)	Number of bits: 8	Address: H'FFFF50
---	----------------------	--------	-------------------	-------------------

Bit	Bit Name	Setting	R/W	Description
3	P13DR	0/1	R/W	0: Pin P13 is set to a low level.
				1: Pin P13 is set to a high level.



Bit	Bit Name	Setting	R/W	Description
7	C/A	1	R/W	Communication Mode
				0: Asynchronous
				1: Clock synchronous
1	CKS1	0	R/W	Clock Select 1, 0
0	CKS0	0	R/W	These bits select the clock source for the baud rate
				generator.
				00: $P\phi$ clock (n = 0)
				For the relation between the settings of these bits and the baud rate, see section 14.3.9, Bit Rate Register (BRR) in the hardware manual. n is the decimal display of the value of n in BRR (see section 14.3.9, Bit Rate Register in the hardware manual).
• Sei	rial control regis	ter 0 (SCR 0)	Number of	bits: 8 Address: H'FFFF82
Bit	Bit Name	Setting	R/W	Description
7	TIE	0/1	R/W	Transmit Interrupt Enable
				0: Disables TXI interrupt requests.
				1: Enables TXI interrupt requests.
6	RIE	0/1	R/W	Receive Interrupt Enable
				0: Disables RXI and ERI interrupt requests.
				1: Enables RXI and ERI interrupt requests.
5	TE	0/1	R/W	Transmit Enable
				0: Disables transmission.
				1: Enables transmission.
4	RE	0/1	R/W	Receive Enable
				0: Disables reception.
				1: Enables reception.
2	TEIE	0/1	R/W	Transmit End Interrupt Enable
				0: Disables TEI interrupt requests.
				1: Enables TEI interrupt requests.
1	CKE1	1	R/W	Clock Enable 1 and 0
0	CKE0	0		Selects the clock source.
				When in clock synchronous mode;
				0X: Internal clock. SCK pin is set as a clock output pin.
				1X: External clock. SCK pin is set as a clock input pin.

Note X: Don't care.

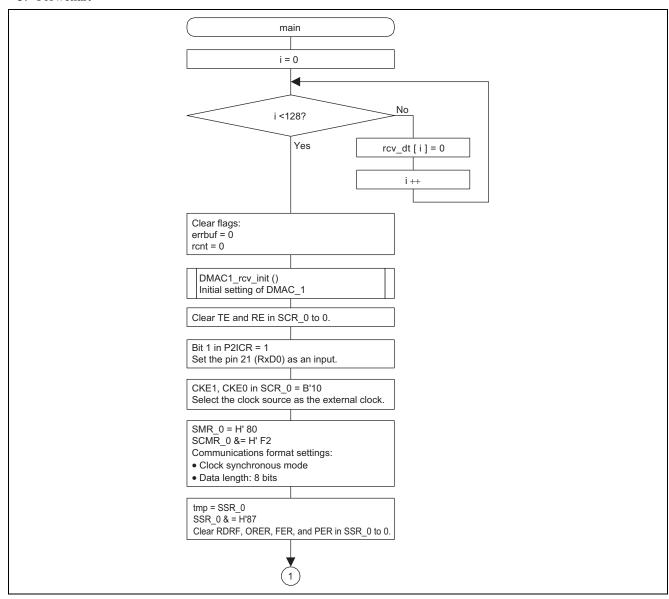


Bit	rial status registe Bit Name	Setting	Number of bit	ts: 8 Address: H'FFFF84 Description
7	TDRE	Undefined	R/(W)*	Transmit Data Register Empty Indicates whether TDR contains data for transmission. [Setting conditions] Clearing of the TE bit in SCR to 0 Transfer of data from TDR to TSR [Clearing conditions] Writing of 0 to TDRE after having read TDRE = 1 (when using an interrupt and having the CPU clear it, be sure to read the flag after having written 0 to it). Generation of a TXI interrupt request allowing DMAC to write transmit data to TDR
6	RDRF	0	R/(W)*	Receive Data Register Full Indicates whether RDR holds received data. [Setting condition] The normal end of serial reception and the transfer of received data from RSR to RDR [Clearing conditions] Writing of 0 to RDRF after having read RDRF = 1 (when using an interrupt and having the CPU clear it, be sure to read the flag after having written 0 to it). Generation of an RXI interrupt request allowing DMAC or DTC to read data from RDR. The RDRF flag is not affected and retains its previous value even though the RE bit in SCR is cleared to 0. Note that when the next reception is completed while the RDRF flag is being set to 1, an overrun error occurs and the received data are lost.
5	ORER	0	R/(W)*	Overrun Error [Setting condition] Occurrence of an overrun error during reception [Clearing condition] Writing of 0 to ORER after having read ORER = 1 (when using an interrupt and having the CPU clear it, be sure to read the flag after having written 0 to it).
2	TEND	Undefined	R	Transmit End [Setting conditions] Clearing of the TE bit in SCR to 0 TDRE = 1 on transmission of the last bit of a character [Clearing conditions] Writing of 0 to TDRE after having read TDRE = 1 Generation of a TXI interrupt request allowing its value DMAC to write data to TDR

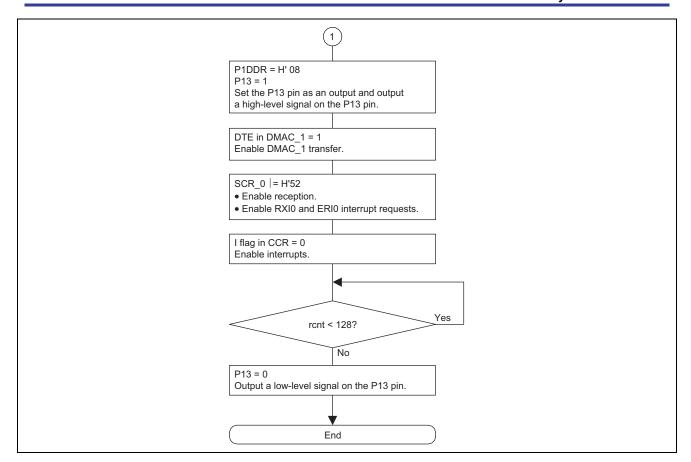
Note: * Only 0 can be written here, to clear the flag.



• Sm	• Smart card mode register_0 (SCMR_0) Number of bits: 8 Address: H'FFFF86				
Bit	Bit Name	Setting	R/W	Description	
0	SMIF	0	R/W	Smart Card Interface Mode Select	
				 Operation is in the normal asynchronous or clock synchronous mode. 	
				1: Operation is in smart card interface mode.	









5.5.3 DMAC1_rcv_init Function

1. Functional overview

DMAC_1 initialization. Sets the transfer processing by RXI0 interrupts from RDR_0 to received data holding area.

2. Argument

None

3. Return value

None

4. Description of internal registers used

The internal registers used in this sample task are described below. The settings shown in these tables are the values used in this sample task and differ from the initial values.

• DMA source address register_1 (DSAR_1) Number of bits: 32 Address: H'FFFC20

Function: DSAR_1 specifies the source address for the transfer.

Setting: &RDR_0

• DMA destination address register_1 (DDAR_1) Number of bits: 32 Address: H'FFFC24

Function: DDAR_1 specifies the destination address for the transfer.

Setting: &rcv_dt

• DMA transfer count register_1 (DTCR_1) Number of bits: 32 Address: H'FFFC2C

Function: DTCR_1 sets the amount of data to be transferred (total amount of transfer).

Setting: 128



Bit	Bit Name	Setting	R/W	Description
31	DTE	0	R/W	Data Transfer Enable
				0: Disables data transfer.
				1: Enables data transfer.
26	NRD	0	R/W	Next Request Delay
				0: Starts accepting the next transfer request after
				completion of the current transfer.
				1: Starts accepting the next transfer request one cycle after
				completion of the current round of transfer.
17	ESIF	0	R/(W)*	Transfer Escape Interrupt Flag
				0: A transfer escape end interrupt request has not been
				issued.
4.0			D //\ 10 t	1: A transfer escape end interrupt request has been issued.
16	DTIF	0	R/(W)*	Data Transfer Interrupt Flag
				0: A transfer end interrupt request by the transfer counter
				has not been issued.
				 A transfer end interrupt request by the transfer counter has been issued.
15	DTSZ1	0	R/W	Data Access Size 1 and 0
14	DTSZ1	0	R/W	00: Data access size for transfer is in bytes (8 bits).
13	MDS1	0	R/W	Transfer Mode Select 1 and 0
12	MDS0	0	R/W	00: Sets the normal transfer mode.
9	ESIE	0	R/W	Transfer Escape Interrupt Enable
3	LOIL	O	17,44	Disables transfer escape interrupt requests.
				Enables transfer escape interrupt requests.
8	DTIE	1	R/W	Data Transfer End Interrupt Enable
Ū		•	,	0: Disables transfer end interrupt requests.
				1: Enables transfer end interrupt requests.
7	DTF1	1	R/W	Data Transfer Factor 1 and 0
6	DTF0	0	R/W	10: DMAC activation source is an on-chip module interrupt.
5	DTA	1	R/W	Data Transfer Acknowledge
				DMA transfer in response to an internal module interrupt,
				this bit enables or disables clearing of the source flag
				selected by DMRSR.
				0: Source flag for the internal module interrupt is not
				cleared.
				1: Source flag for the internal module interrupt is cleared.

Note: * Only 0 can be written here, to clear the flag.



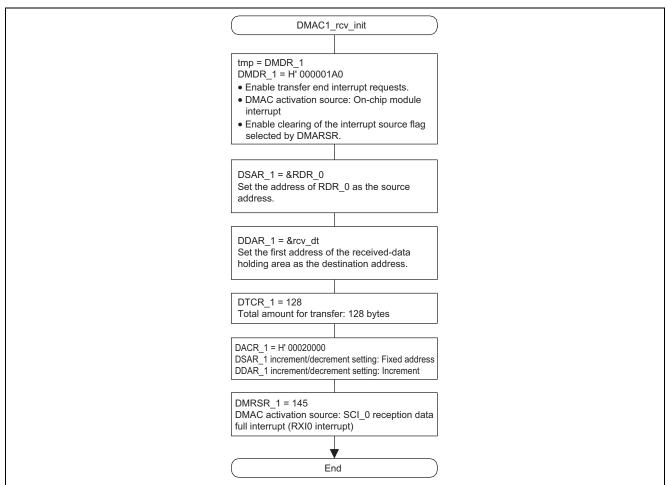
• DN	MA address conti	rol register_1	(DACR_1)	Number of bits: 32 Address: H'FFFC38
Bit	Bit Name	Setting	R/W	Description
31	AMS	0	R/W	Address Mode Select
				0: Dual address mode
				1: Single address mode
21	SAT1	0	R/W	Source Address Update Mode 1 and 0
20	SAT0	0	R/W	00: Source address is fixed.
17	DAT1	1	R/W	Destination Address Update Mode 1 and 0
16	DAT0	0	R/W	10: Increments the source address.

• DMA module request select register_1 (DMRSR_1) Number of bits: 8 Address: H'FFFD21

Function: DMRSR_1 specifies the source of on-chip module interrupts. The setting 145 corresponds to DMAC

activation by SCI_0 received data full interrupts (RXI0 interrupts).

Setting: 145





5.5.4 dmtend1_int Function

1. Functional overview

Handler for the DMAC_1 transfer end interrupt. Sets SCI_0 reception disabled, RXI0 and ERI0 interrupt requests, and DMAC_1 transfer end interrupt requests disabled.

2. Argument

None

3. Return value

None

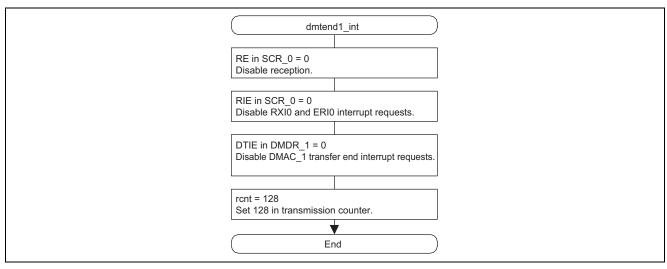
4. Description of internal registers used

The internal registers used in this sample task are described below. The settings shown in these tables are the values used in this sample task and differ from the initial values.

• Serial control register_0 (SCR_0) Number of bits: 8 Address: H'FFFF82

Bit	Bit Name	Setting	R/W	Description	
6	RIE	0	R/W	Receive Interrupt Enable	
				0: Disables RXI and ERI interrupt requests.	
				1: Enables RXI and ERI interrupt requests.	
4	RE	0	R/W	Receive Enable	
				0: Disables reception.	
				1: Enables reception.	

DMA mode control register _1 (DMDR_1)
 Bit Bit Name Setting R/W Description
 BTIE 0 R/W Data Transfer End Interrupt Enable
 Disables transfer end interrupt requests.
 Enables transfer end interrupt requests.





5.5.5 eri0_int Function

1. Functional overview

Handler for SCI_0 reception error interrupts (ERI0 interrupt). Writes error data to RAM and initializes SSR_0.

2. Argument

None

3. Return value

None

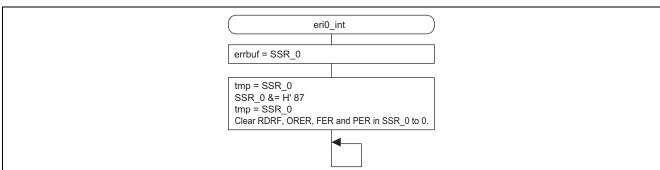
4. Description of internal registers used

The internal registers used in this sample task are described below. The settings shown in these tables are the values used in this sample task and differ from the initial values.

• Serial status register 0 (SSR 0) Number of bits: 8 Address: H'FFFF84

	iai status registe	- \ - /	Nulliber of bi	
Bit	Bit Name	Setting	R/W	Description
6	RDRF	0	R/(W)*	 Receive Data Register Full Indicates whether RDR holds received data. [Setting condition] The normal end of serial reception and the transfer of received data from RSR to RDR [Clearing conditions] Writing of 0 to RDRF after having read RDRF = 1 (when using an interrupt and clearing by CPU, be sure to read a flag after having written 0.) Generation of an RXI interrupt request allowing DMAC or DTC to read data from RDR. The RDRF flag is not affected and retains its previous value even though the RE bit in SCR is cleared to 0. Note that when the next reception is completed while the RDRF flag is being set to 1, an overrun error occurs and the received data are lost.
5	ORER	0	R/(W)*	Overrun Error [Setting condition] Occurrence of an overrun error during reception [Clearing condition] Writing of 0 to ORER after having read ORER = 1 (when using an interrupt and clearing by CPU, be sure to read a flag after having written 0.)

Note: * Only 0 can be written here, to clear the flag.





6. Documents for Reference (Note)

- Hardware Manual
 H8SX/1653 Group Hardware Manual
 The most up-to-date version of this document is available on the Renesas Technology Website.
- Technical News/Technical Update
 The most up-to-date information is available on the Renesas Technology Website.



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Revision Record

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